



<b>Title of Change:</b>	Adding backside tape to the current WLCSP package - TCC-303A-RT	
<b>Proposed first ship date:</b>	1 December 2017 or earlier upon customer approval	
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Scott.Haddow@onsemi.com>	
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office	
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Scott.Haddow@onsemi.com>	
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
<b>Change Part Identification:</b>	Affected products will be identified by the data code and the trace code of device marking.	
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other <u>Back grinding</u>	
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____	
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Niigata, Japan ON Seremban, Malaysia <input type="checkbox"/> External Foundry/Subcon site(s)	
<b>Description and Purpose:</b>		
This Notification announces the following: <ol style="list-style-type: none"> <li>Backside coating will be added to the TCC-303 part to improve the robustness of the die, and prevent die cracking</li> <li>The LINTEC ADWILL LC282H BSP tape used for the back side coating, as well as the coating process itself, are qualified for other products at Niigata site</li> <li>The WLCSP package size after applying the backside tape is changed from 1.376X1.025X0.65 (mm) to 1.376X1.025X0.675 (mm). The Case outline (567MV) has been updated, so has the datasheet of the product.</li> </ol>		
	<b>Before Change</b>	<b>After Change</b>
	<b>Description</b>	<b>Description</b>
BACKSIDE COATING	NA	LINTEC ADWILL LC282H BSP tape



**Reliability Data Summary:**

The reliability of the product is qualified by similarity using the reliability data from the LC898214XC-MH product.

**QV DEVICE NAME** LC898214XC-MH

**PACKAGE** WLCSP8

Test	Specification	Condition	Interval	Results
HTSL	JESD22-A103	Ta= 150°C	1000 hrs	0/75
PC	J-Std-020 JESD22-A113	MSL1 @ 85°C	168 hrs	0/225
THB	JESD22-A101	Ta = 85°C, 85% RH, VccMax	1008 hrs	0/75
AC	JESD22-A102	Ta = 121°C, 100% RH, 15psig, unbiased	96 hrs	0/75
TC	JESD22-A104	Ta = -65°C to 150°C	500cyc	0/75

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

**List of affected Standard Parts:**

Part Number	Qualification Vehicle
TCC-303A-RT	LC898214XC-MH